

**SYNOPSYS®**

# Challenges for stochastic EUV lithography simulation

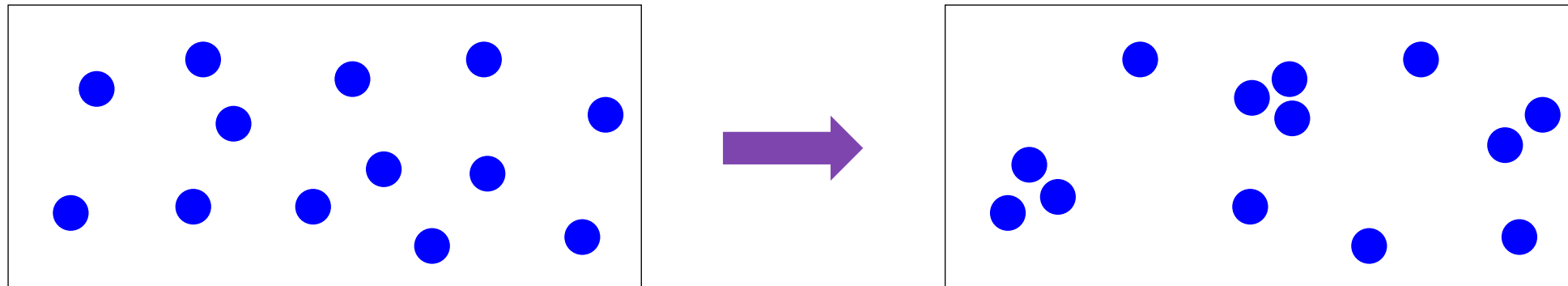
## EUVL Workshop

Ulrich Welling, Lawrence Melvin III, Hans-Jürgen  
Stock

Leuven, June 6<sup>th</sup> 23

# Starting from a Question

How does aggregation of PAG or Quencher in PR affect the lithographic process?



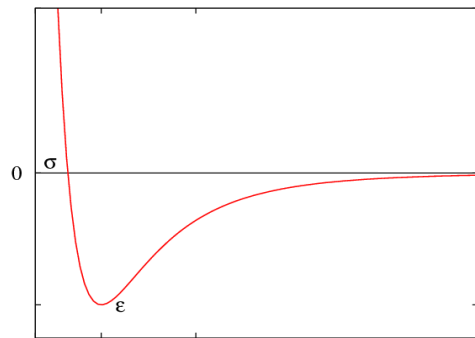
**Attempt to give an informed in-silico answer based on:**  
particle simulations  
lithographic process simulation

# Aggregation

Aggregation is caused by PAG molecule interaction in the PR Matrix.

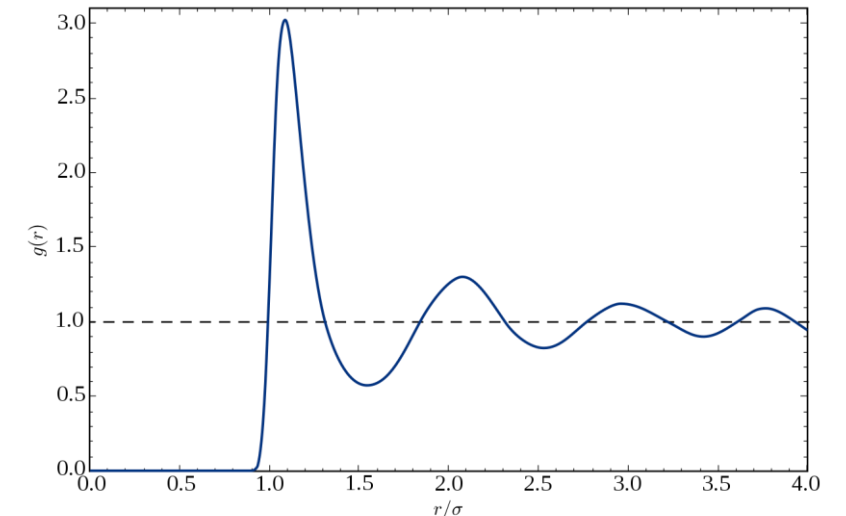
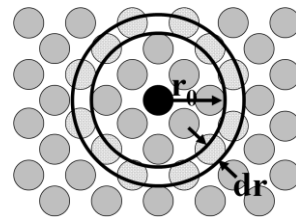
Characterized by the radial distribution function (RDF)  
( probability of finding another particle at distance  $r$  of a central particle )

$$\Phi_{12}(r) = 4\epsilon \left[ \left( \frac{\sigma}{r} \right)^{12} - \left( \frac{\sigma}{r} \right)^6 \right]$$



Lennard-Jones 12/6 potential

$$g(\mathbf{r}) = \frac{1}{\rho} \left\langle \sum_{i \neq 0} \delta(\mathbf{r} - \mathbf{r}_i) \right\rangle$$

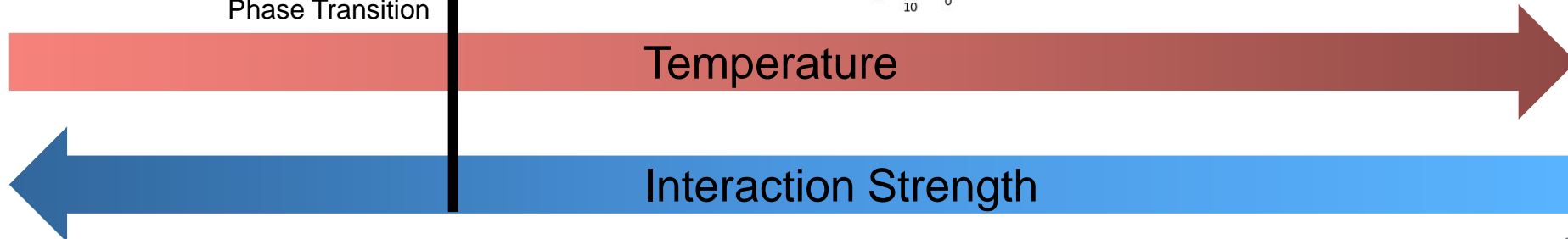
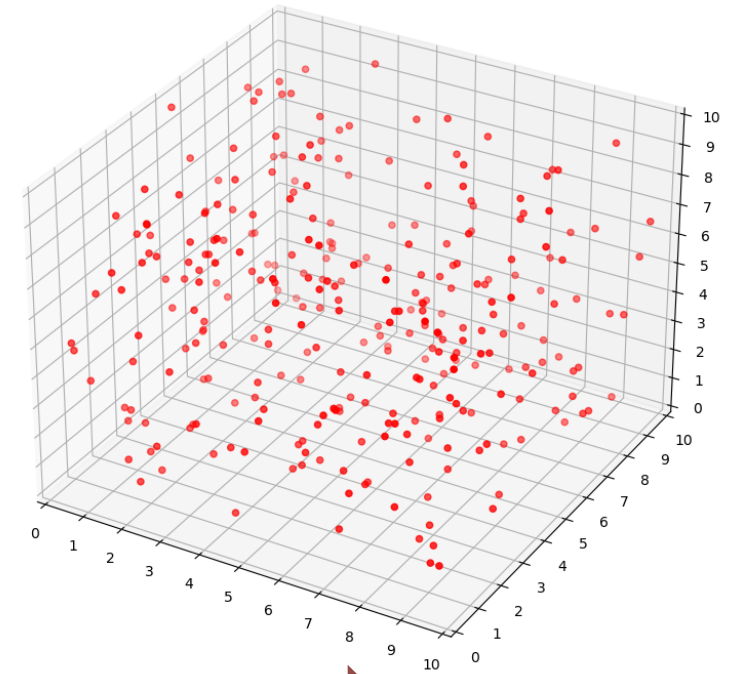
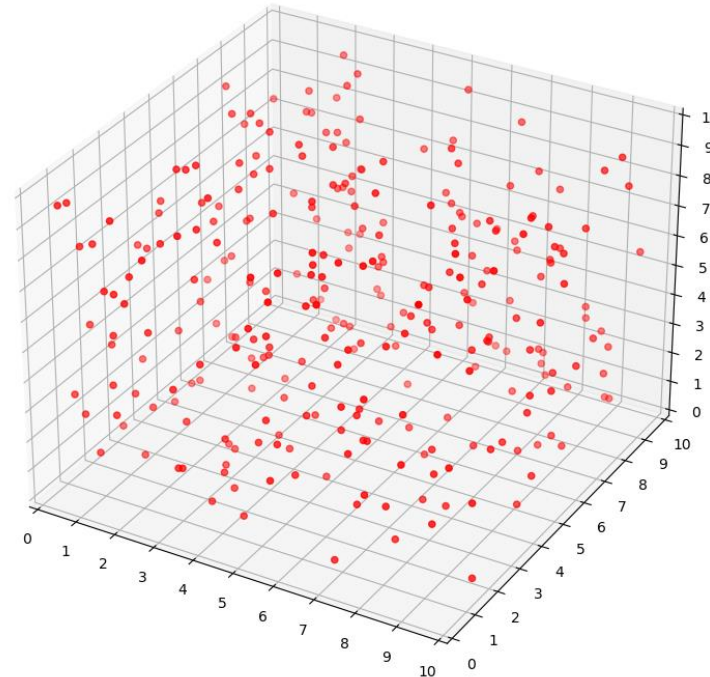
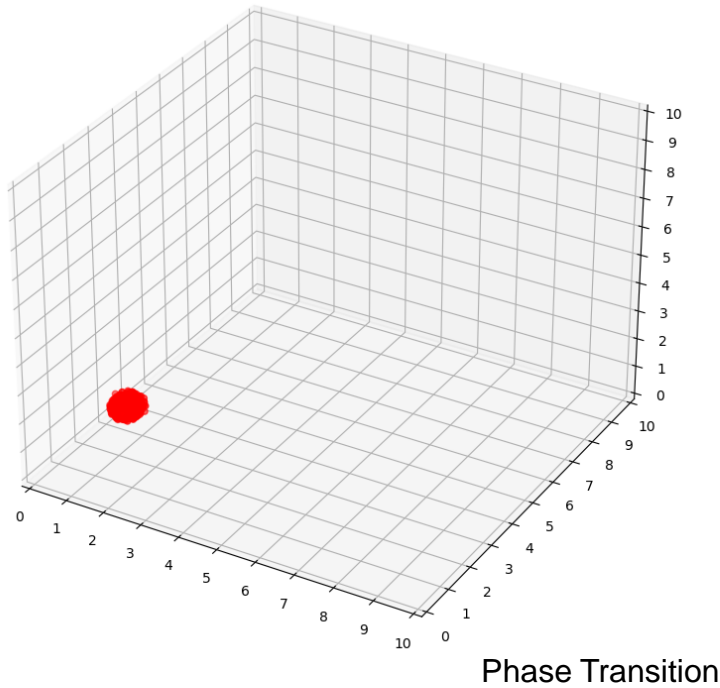


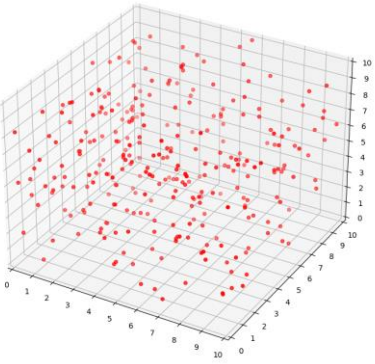
RDF of Lennard-Jones fluid

# PAG Model System

*Brownian Motion simulation of LJ fluid, based on ref. PR quantities as model for PAG distribution*

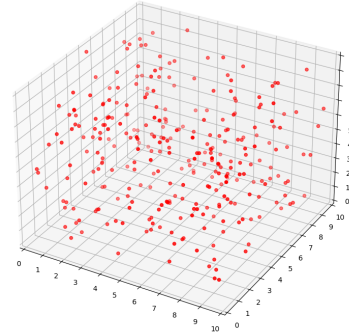
$$c(\text{PAG}) = 0.3/\text{nm}^3 \quad \epsilon_{\{\min\}} = 0.5\text{nm}$$



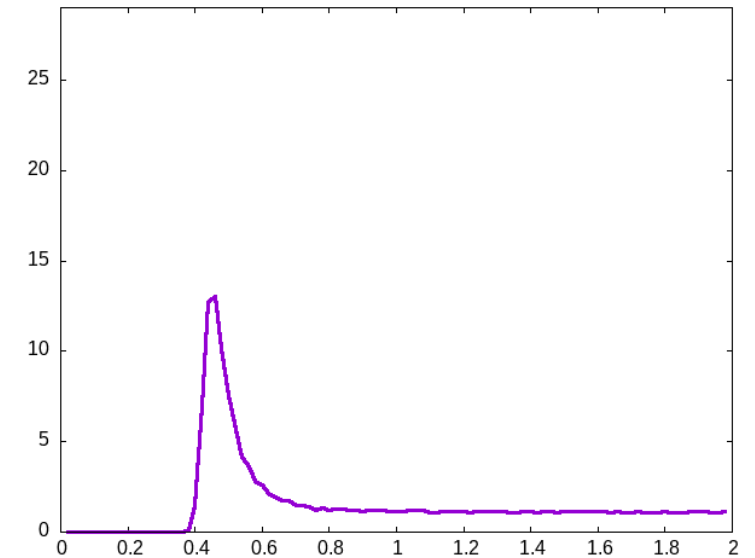
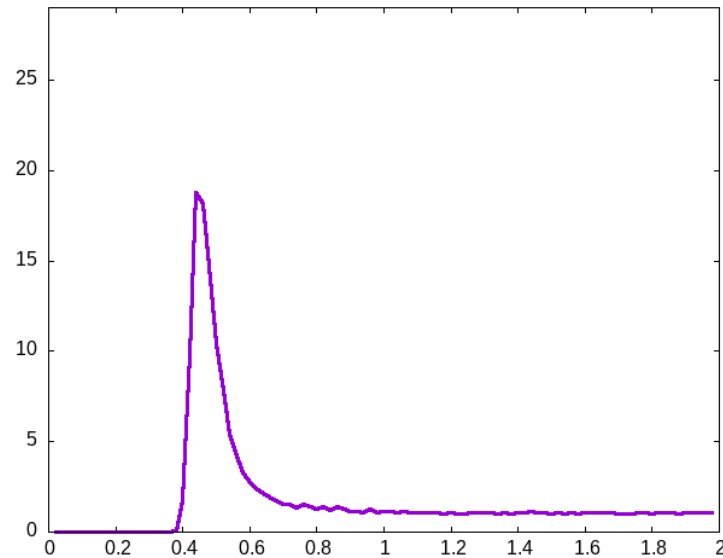
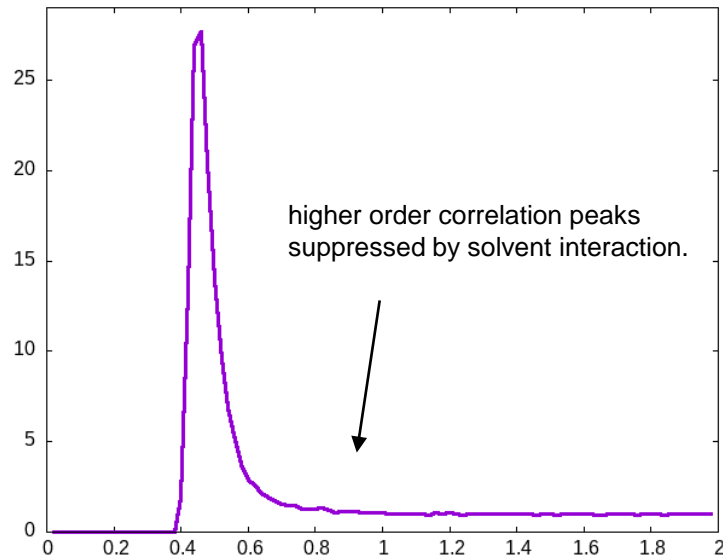


# Microscopic Structure

*model temperature + interaction modifies local aggregation*

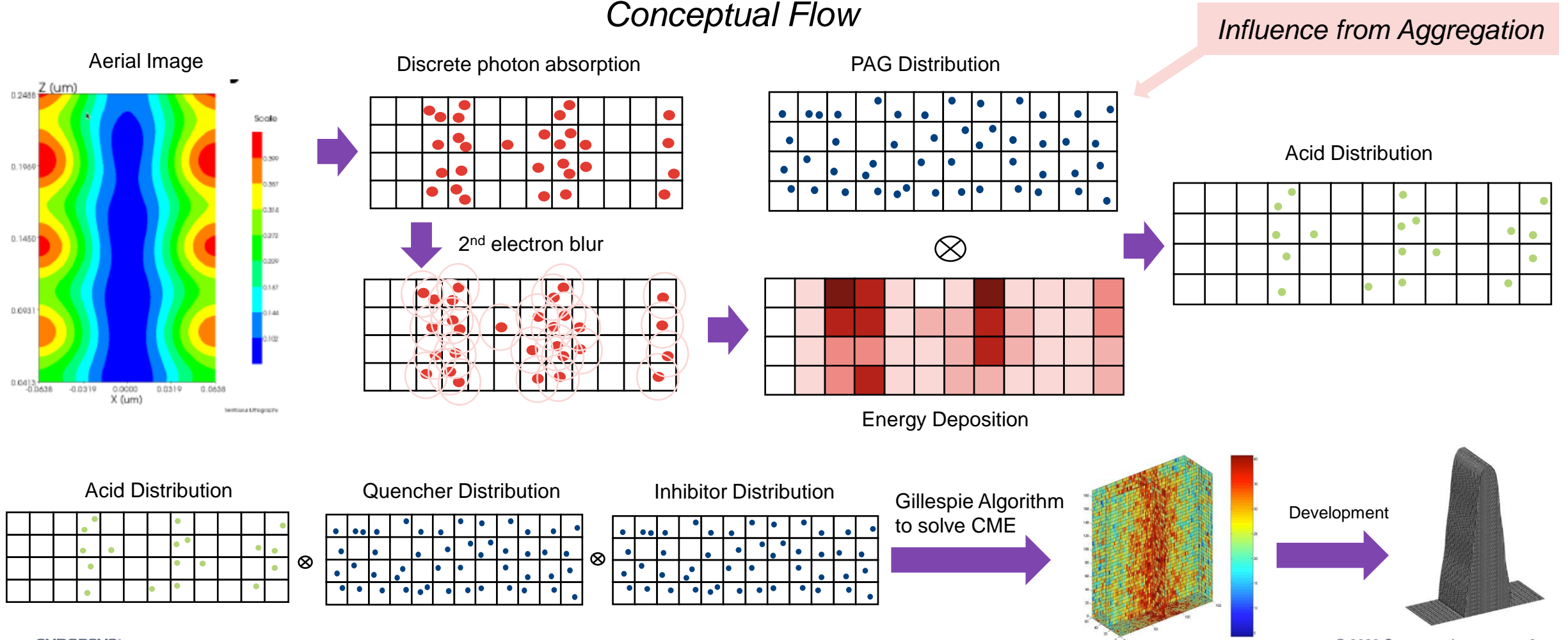


RDF



# Stochastic Lithography Simulation

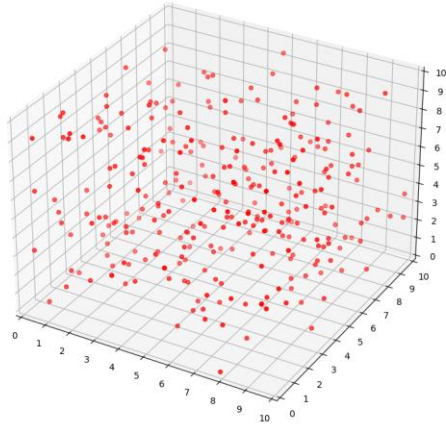
## Conceptual Flow



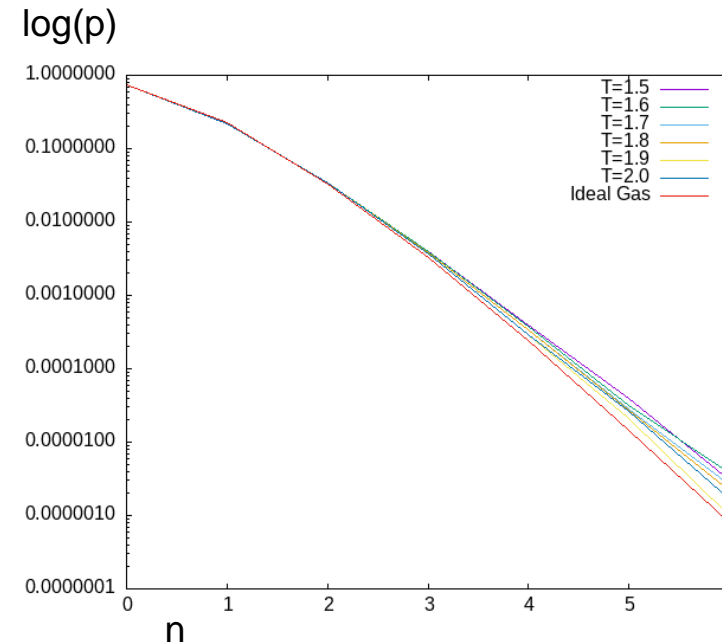
# Relating microscopic structure and lattice-based distribution

*particle based model system gives access to required information*

Particle Distribution



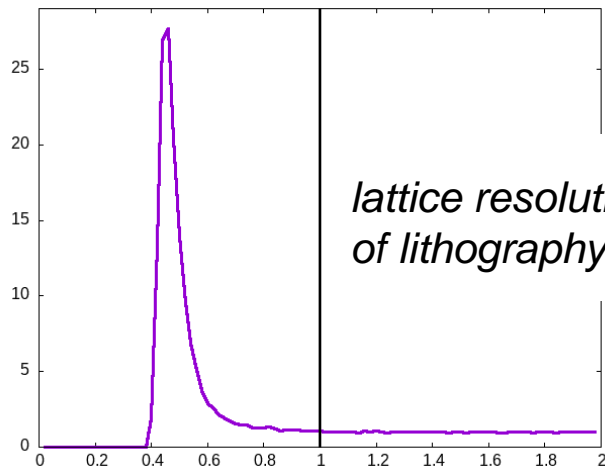
Histogram of particle count in 1nm<sup>3</sup> lattice cells



*the impact is small, difference is in the weight of tails*

cluster size generated from binomial distribution matching observed particle number histograms

RDF



*lattice resolution of lithography model*

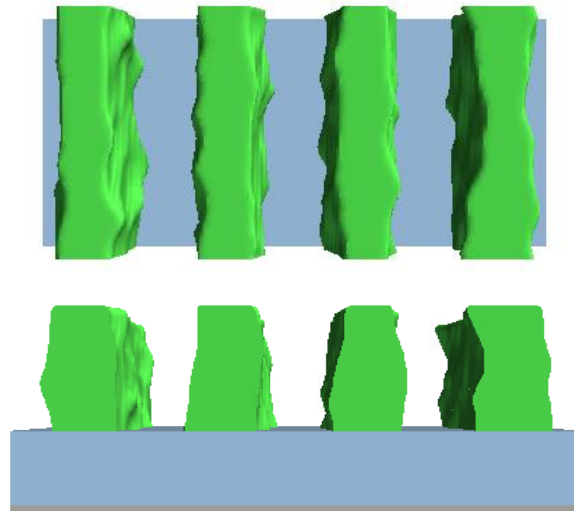
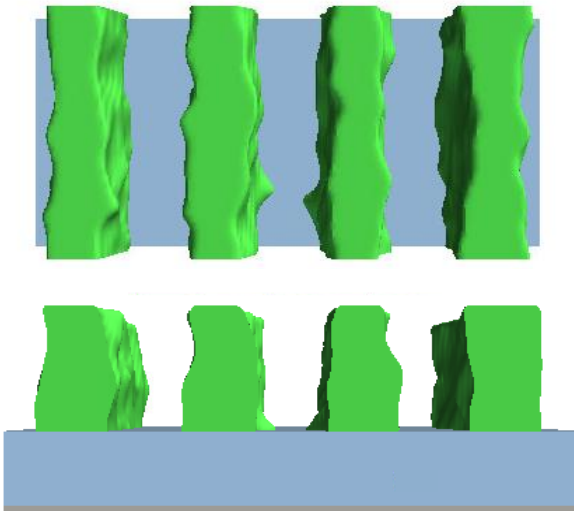
# Impact on Lithography Simulation

*Modified initial PAG distribution leads to very small changes in roughness*

EUV PTD resist, P36 L/S, NXE:3300, IMEC PR

No Interaction

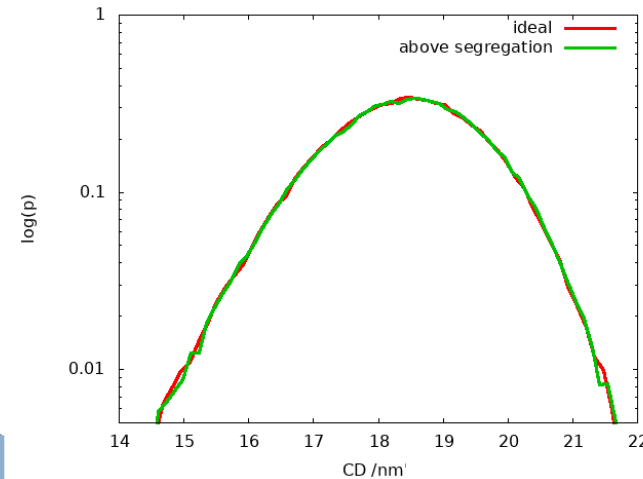
T close to segregation



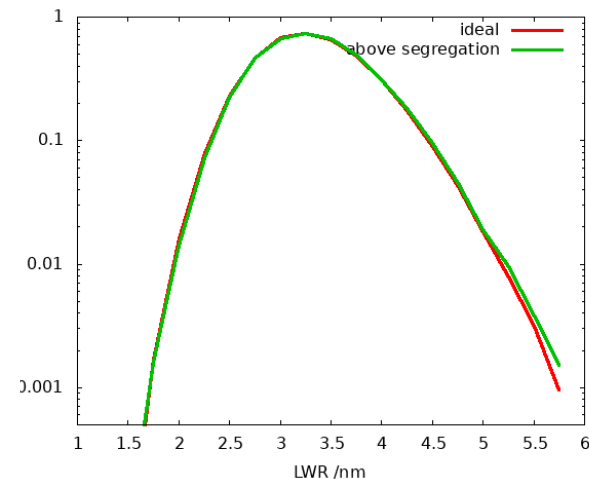
CD: 18.450nm  
LWR: 3.462nm

CD: 18.439nm  
LWR: 3.473nm

CD



LWR



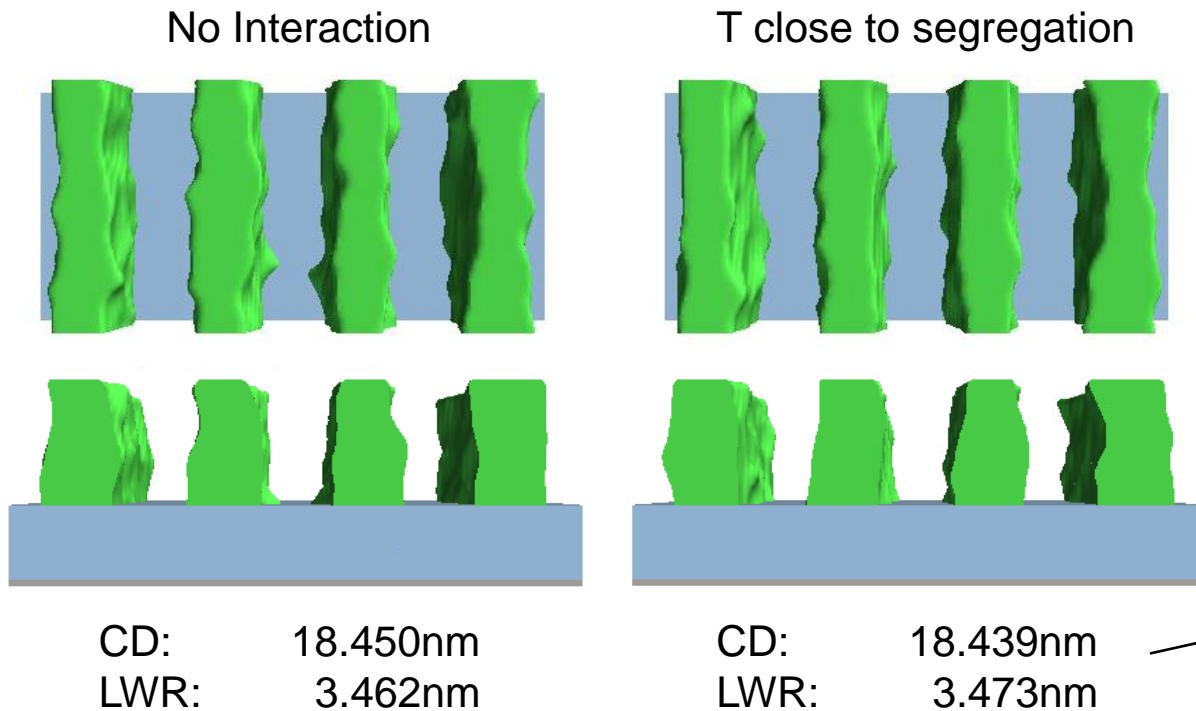
no difference in CD,  
slightly increased chance of higher LWR

Is this an effect or noise?

# Impact on Lithography Simulation

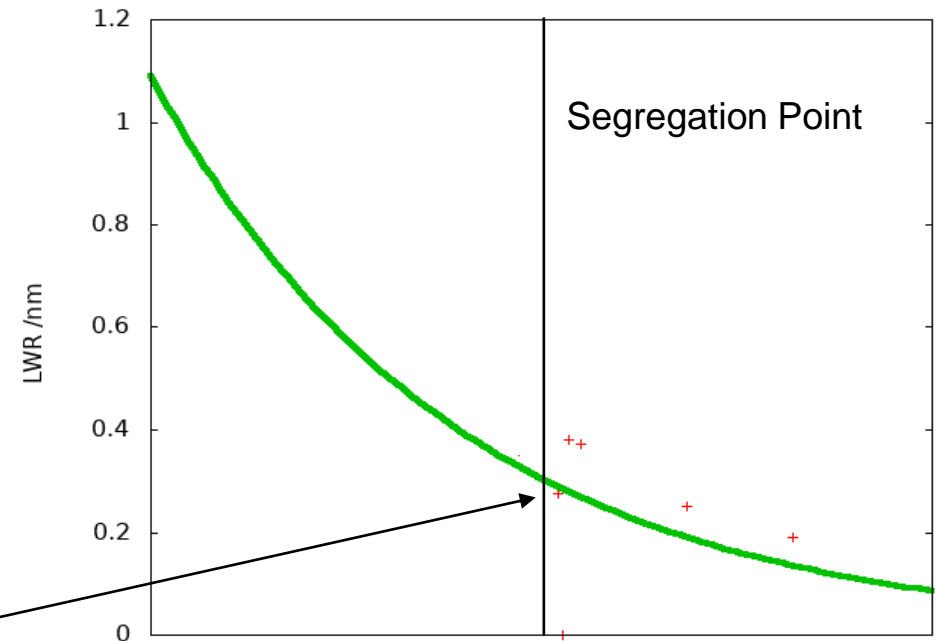
*Modified initial PAG distribution leads to very small changes in roughness*

EUV PTD resist, P36 L/S, NXE:3300, IMEC PR



Added LWR: 0.36nm  
(assuming added LWR to be uncorrelated noise)

### LWR contribution from Aggregation



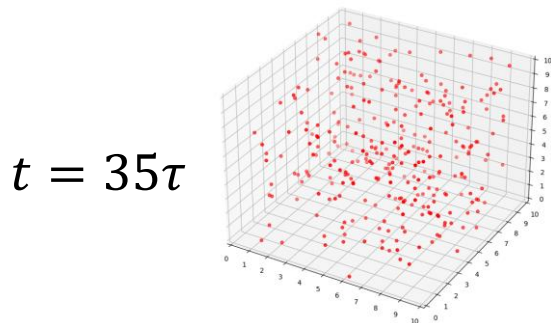
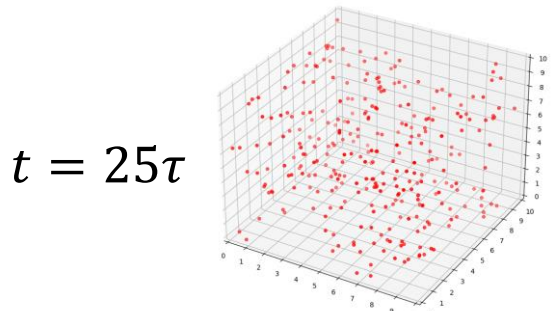
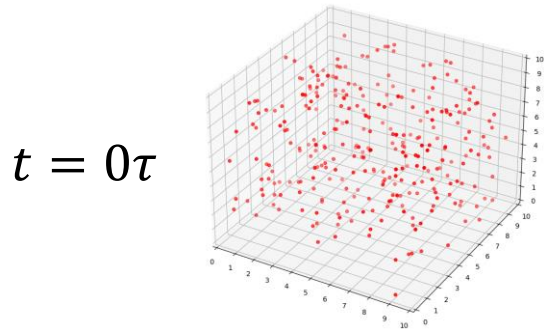
Modified Cluster Size Distribution (N,p)

Temperature

Interaction Strength

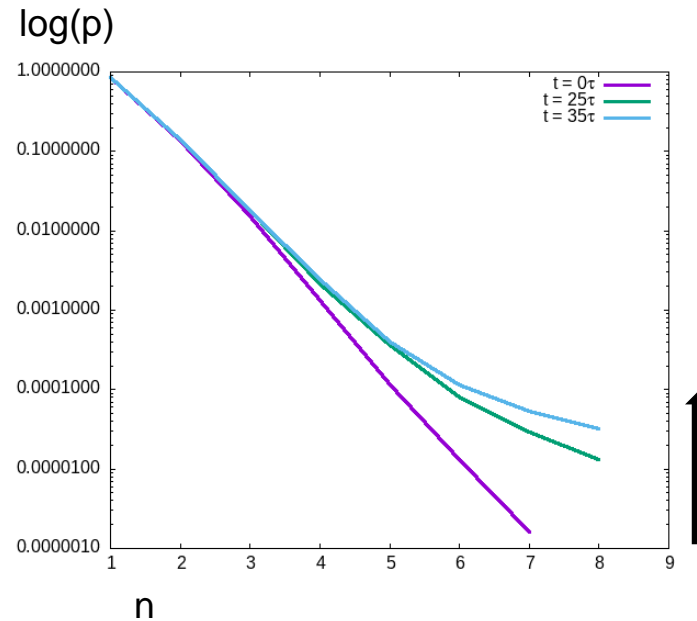
# Impact of Solvent Evaporation Process

*Assumption: PAG solubility switches below Segregation Point during Post Apply Bake*



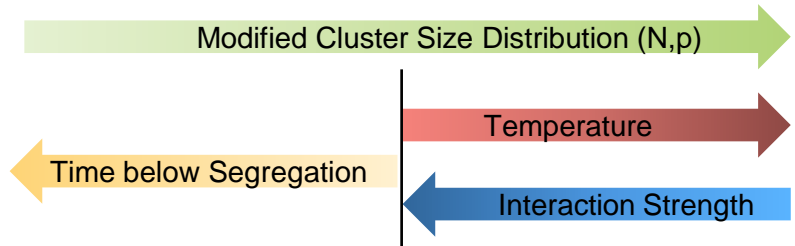
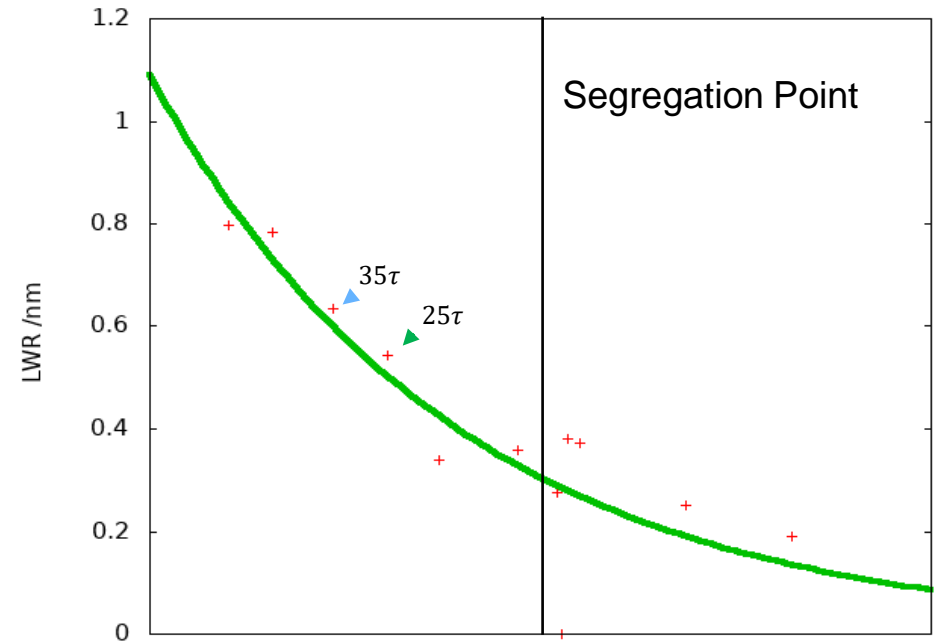
$\tau$  corresponds to 1-10s for typical PAG diffusion rates

Quenching a system leads to increased probabilities of larger aggregations.



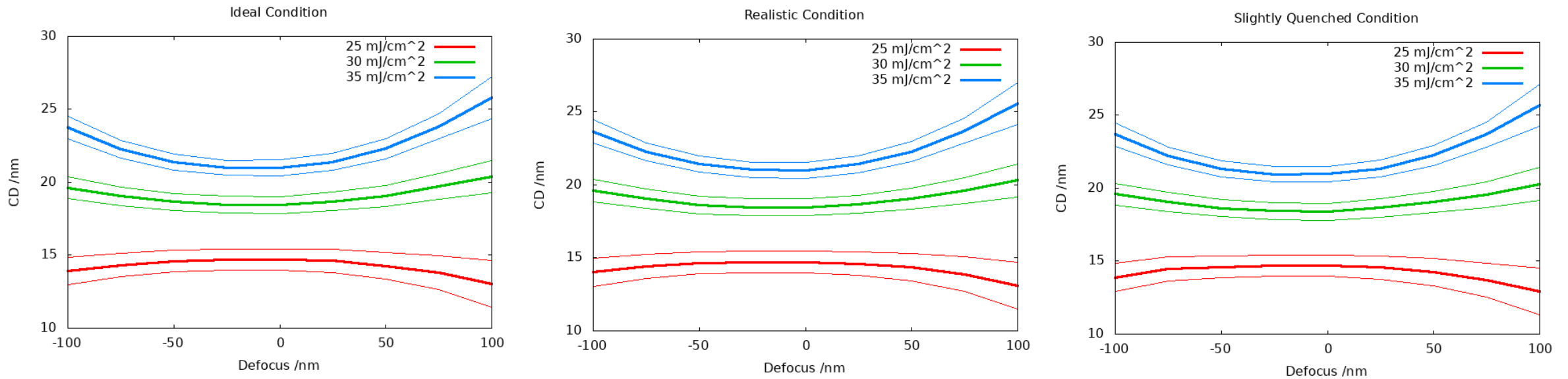
The initial stage of a quenching process has an impact on LWR before the particle distributions vary substantially

## LWR contribution from Aggregation



# Process Window Impact

*36P18 L/S PW for ideal, realistic and slightly quenched PAG distribution*



*No visible impact on process window for the considered cases.*

# Conclusions

- Demonstration of a pathway to include Aggregation Effects to lattice-based stochastic lithography simulations
- LJ model implies aggregation *does not affect* the process above the segregation point: short-range pair correlations do not affect process quality
- PAG molecule segregation due to solvent evaporation / slow cooling after Post Apply Bake could have severe impact on PR performance : *experiments needed*

*diffraction experiments + detailed atomistic simulations could provide insight in distributions needed to inform litho-process simulations*

# Acknowledgements



Peter de Bisshop



Guido Germano



*Sentaurus Lithography*

Thomas Mülders

Balint Meliorisz

Wolfgang Demmerle

Ulrich Klostermann

*Mask Solutions*

Zac Levinson

*Quantum-ATK*

Julian Schneider